



Material Content Data Sheet



Halogen-Free

Sales Product Name	BGM 13HBA9 E6327	Issued	27. April 2022
MA#	MA005715344		
Package	PG-ATSLP-9-1	Weight*	1.13 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.149	13.21	13.21	132100	132100
bumps	non noble metal	copper	7440-50-8	0.010	0.91	0.91	9056	9056
encapsulation	organic material	carbon black	1333-86-4	0.003	0.28		2767	
	plastics	epoxy resin	-	0.070	6.23		62258	
	inorganic material	silicondioxide	60676-86-0	0.447	39.59	46.10	396142	461167
leadfinish	noble metal	gold	7440-57-5	0.022	1.97		19699	
	non noble metal	nickel	7440-02-0	0.025	2.25	4.22	22466	42165
substrate	organic material	carbon black	1333-86-4	0.001	0.05		473	
	plastics	epoxy resin	-	0.021	1.85		18452	
	inorganic material	silicondioxide	60676-86-0	0.157	13.88		138782	
	non noble metal	copper	7440-50-8	0.174	15.44	31.22	154360	312067
solder	noble metal	silver	7440-22-4	0.000	0.01		59	
	non noble metal	tin	7440-31-5	0.004	0.32	0.33	3225	3284
ubm	non noble metal	tungsten	7440-33-7	0.000			26	
	non noble metal	titanium	7440-32-6	0.000			49	
	non noble metal	copper	7440-50-8	0.000	0.01	0.01	137	212
solder resists	inorganic material	silicondioxide	60676-86-0	0.010	0.85		8489	
	inorganic material	bariumsulfate	7727-43-7	0.010	0.86		8589	
	plastics	acrylic resin	-	0.026	2.29	4.00	22871	39949
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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